

L Number	Hits	Search Text	DB	Time stamp
1	9539	die near5 (attach or attaching or attachment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 11:08
2	10693	cyanoacrylate or cyano near2 acrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 11:08
3	65	(die near5 (attach or attaching or attachment)) and (cyanoacrylate or cyano near2 acrylate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 11:59
4	28539	anaerobic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 11:59
5	1226446	lead or leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 11:59
6	3722	leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:03
7	1227249	(lead or leads) or leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:03
8	707	anaerobic same ((lead or leads) or leadframe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:03
9	850838	adhesive or glue	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:03
10	48	(anaerobic same ((lead or leads) or leadframe)) same (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:03
11	528069	chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:03
12	406546	die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:04
13	891770	chip or die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:04
14	11	((anaerobic same ((lead or leads) or leadframe)) same (adhesive or glue)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 12:05

L Number	Hits	Search Text	DB	Time stamp
1	3722	leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 09:54
2	535077	chip or semiconductor near5 die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 09:55
3	2062	leadframe same (chip or semiconductor near5 die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 09:55
4	9601	cyanoacrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 09:55
5	13	(leadframe same (chip or semiconductor near5 die)) and cyanoacrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:07
6	62956	frame) near5(lead or leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:21
7	19589	(chip or semiconductor near5 die) same (frame) near5(lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:08
8	27	cyanoacrylate and ((chip or semiconductor near5 die) same (frame) near5(lead or leads))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:19
9	1	leadframe	USOCR	2003/04/30 10:19
10	24900	chip	USOCR	2003/04/30 10:19
11	210	cyanoacrylate	USOCR	2003/04/30 10:19
12	7	chip and cyanoacrylate	USOCR	2003/04/30 10:20
13	18811	semiconductor	USOCR	2003/04/30 10:20
14	1	semiconductor and cyanoacrylate	USOCR	2003/04/30 10:20
15	62956	frame) near5(lead or leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:22
16	3354585	bonded or attached or attaching or attachment or attach or bond or bonds or bonding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:22
17	62956	frame near5(lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:23
18	1594	(leadframe same (chip or semiconductor near5 die)) same (bonded or attached or attaching or attachment or attach or bond or bonds or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:23
19	850838	adhesive or glue	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:23

20	411	((leadframe same (chip or semiconductor near5 die)) same (bonded or attached or attaching or attachment or attach or bond or bonds or bonding)) same (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:23
21	146	superglue	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:24
22	0	((((leadframe same (chip or semiconductor near5 die)) same (bonded or attached or attaching or attachment or attach or bond or bonds or bonding)) same (adhesive or glue)) and superglue	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:24
23	204456	acrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:24
24	211033	cyanoacrylate or acrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:24
25	64	superglue and (cyanoacrylate or acrylate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:26
26	10	((((leadframe same (chip or semiconductor near5 die)) same (bonded or attached or attaching or attachment or attach or bond or bonds or bonding)) same (adhesive or glue)) and (cyanoacrylate or acrylate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:28
27	7805	radiopaque	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:29
28	0	radiopaque and (((leadframe same (chip or semiconductor near5 die)) same (bonded or attached or attaching or attachment or attach or bond or bonds or bonding)) same (adhesive or glue))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:29
29	0	radiopaque and (leadframe same (chip or semiconductor near5 die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:29
30	606	radiopaque and cyanoacrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:30
31	0	(radiopaque and cyanoacrylate) and leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:30
32	0	(radiopaque and cyanoacrylate) and (frame near5(lead or leads))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 10:30

15	451	((lead or leads) and acrylate) and semiconductor) and (adhesive same acrylate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:24
16	1	adhasive same cyanoacrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:25
17	5418	adhesive same cyanoacrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:25
18	528069	chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:25
19	51	(adhesive same cyanoacrylate) same chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:26
20	5830	fast near7 (cure or curing or cured or cures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:27
21	2212	quick near7 (cure or curing or cured or cures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:27
22	7842	((fast near7 (cure or curing or cured or cures)) or (quick near7 (cure or curing or cured or cures)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:27
23	2	((fast near7 (cure or curing or cured or cures)) or (quick near7 (cure or curing or cured or cures))) and ((adhesive same cyanoacrylate) same chip )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:27

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1	9601	cyanoacrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:17
2	1227249	lead or leads or leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:17
3	2719	cyanoacrylate and (lead or leads or leadframe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:18
4	286	cyanoacrylate same (lead or leads or leadframe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:18
5	1226446	lead or leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:18
6	285	cyanoacrylate same (lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:19
7	1220310	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:19
8	26	(cyanoacrylate same (lead or leads)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:19
9	3722	leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:19
10	5	leadframe and ((cyanoacrylate same (lead or leads)) and semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:23
11	204456	acrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:23
12	39108	(lead or leads) and acrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:23
13	3408	((lead or leads) and acrylate) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:24
14	21332	adhesive same acrylate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/30 08:24